

ISP817 Series

DIP4, DC Input, Photo Transistor Coupler

Description

The ISP817 series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a silicon planar phototransistor detector in a plastic DIP4 package with different lead forming options.

With the robust coplanar double mold structure, ISP817 series provide the most stable isolation feature.

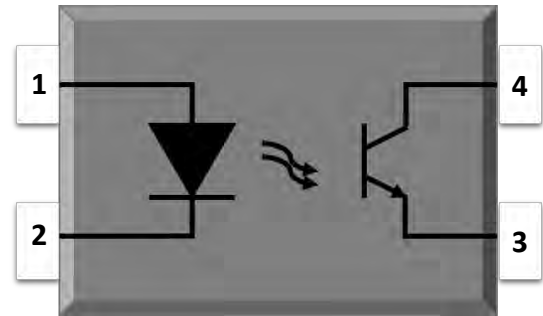
Features

- High isolation 5000 VRMS
- CTR flexibility available see order information
- DC input with transistor output
- Operating temperature range - 55 °C to 110 °C
- RoHS & REACH Compliance
- MSL class 1
- Halogen free (Optional)
- Regulatory Approvals
 - UL - UL1577
 - VDE - EN60747-5-5(VDE0884-5)
 - CQC - GB4943.1, GB8898
 - cUL- CSA Component Acceptance Service Notice No. 5A

Applications

- Switch mode power supplies
- Programmable controllers
- Household appliances
- Office equipment

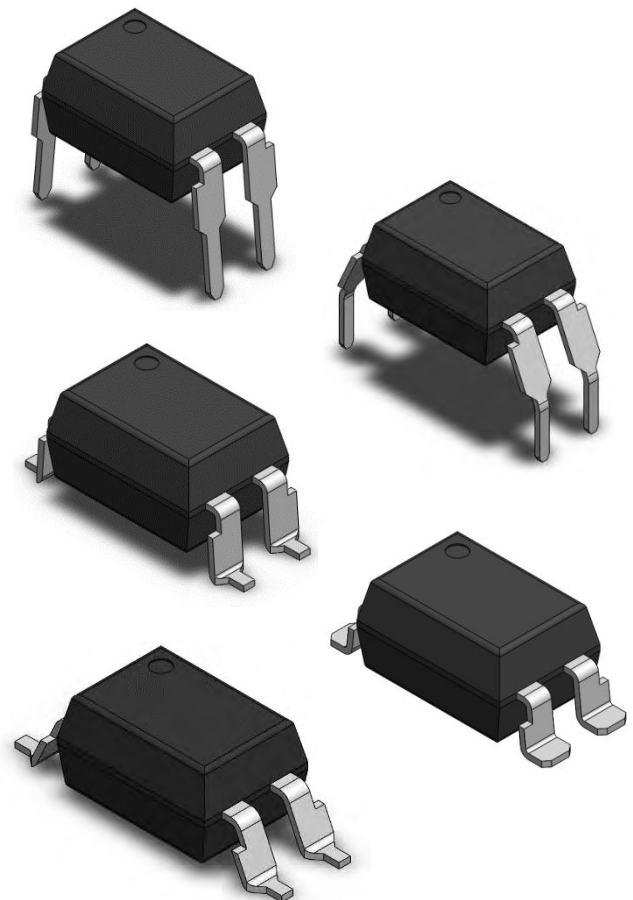
SCHEMATIC

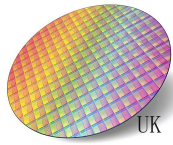


PIN DEFINITION

1. Anode
2. Cathode
3. Emitter
4. Collector

PACKAGE OUTLINE





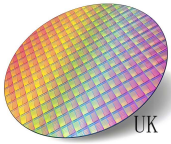
DIP4, DC Input, Photo Transistor Coupler

ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	VALUE	UNIT	NOTE
INPUT				
Forward Current	I_F	60	mA	
Peak Forward Current	I_{FP}	1	A	1
Reverse Voltage	V_R	6	V	
Input Power Dissipation	P_I	100	mW	
OUTPUT				
Collector - Emitter Voltage	V_{CEO}	35	V	
Emitter - Collector Voltage	V_{ECO}	6	V	
Collector Current	I_C	50	mA	
Output Power Dissipation	P_O	150	mW	
COMMON				
Total Power Dissipation	P_{tot}	200	mW	
Isolation Voltage	V_{iso}	5000	V _{rms}	2
Operating Temperature	T_{opr}	-55~110	°C	
Storage Temperature	T_{stg}	-55~125	°C	
Soldering Temperature	T_{sol}	260	°C	

Note 1. 100µs pulse, 100Hz frequency

Note 2. AC For 1 Minute, R.H. = 40 ~ 60%



TEST CIRCUITS

Fig.12 Test Circuits of Response Time

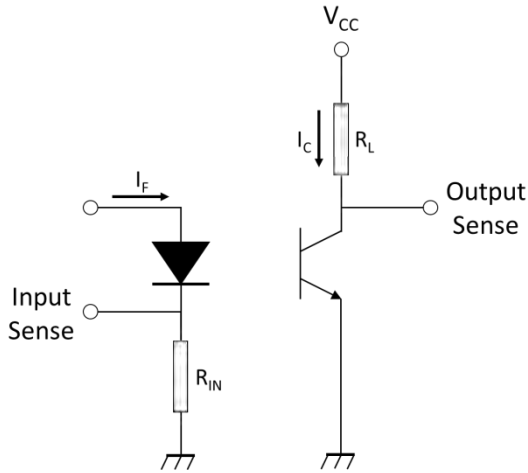


Fig.13 Curves of Response Time

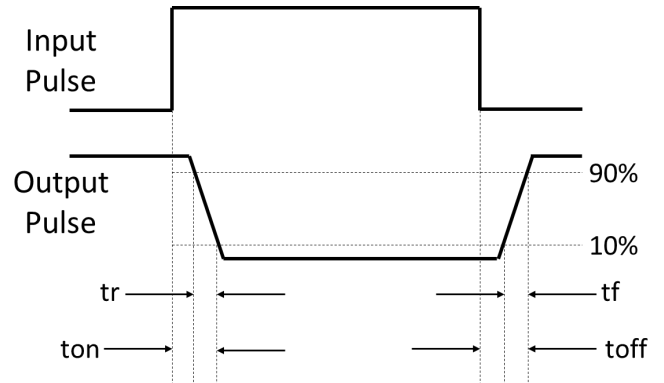
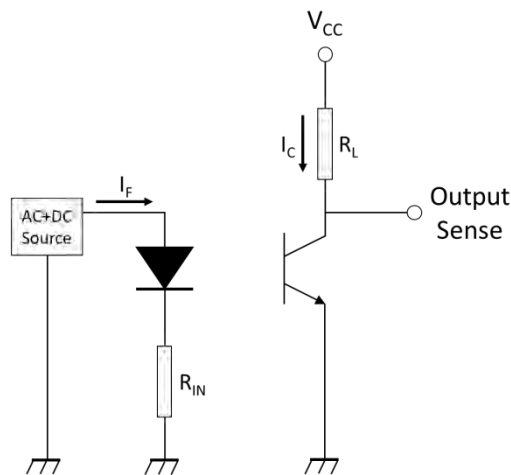
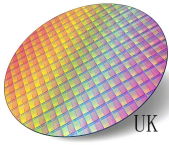


Fig.14 Test Circuits of Frequency Response

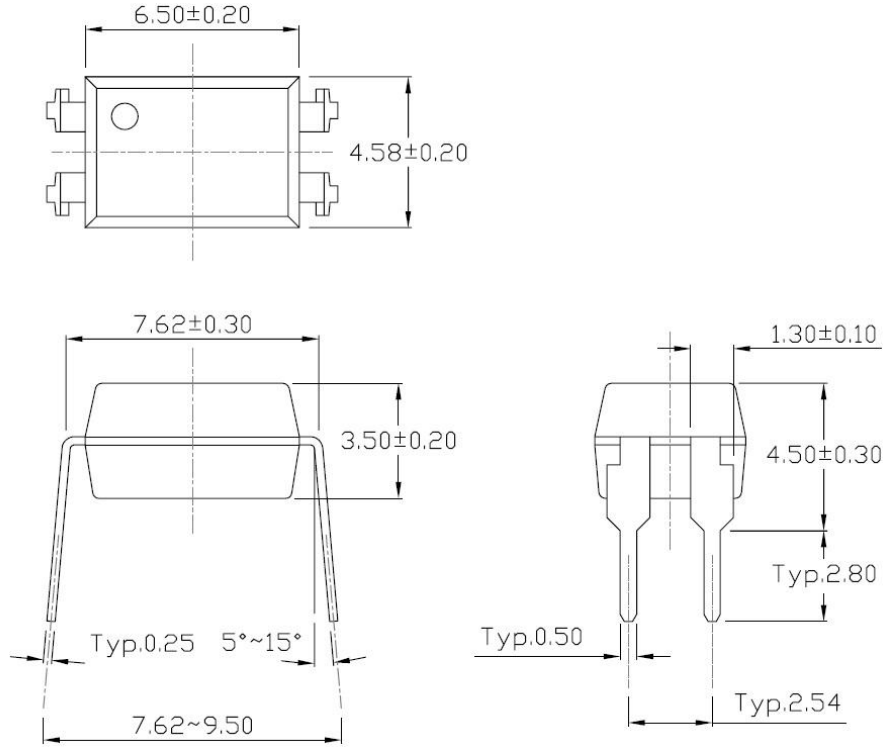




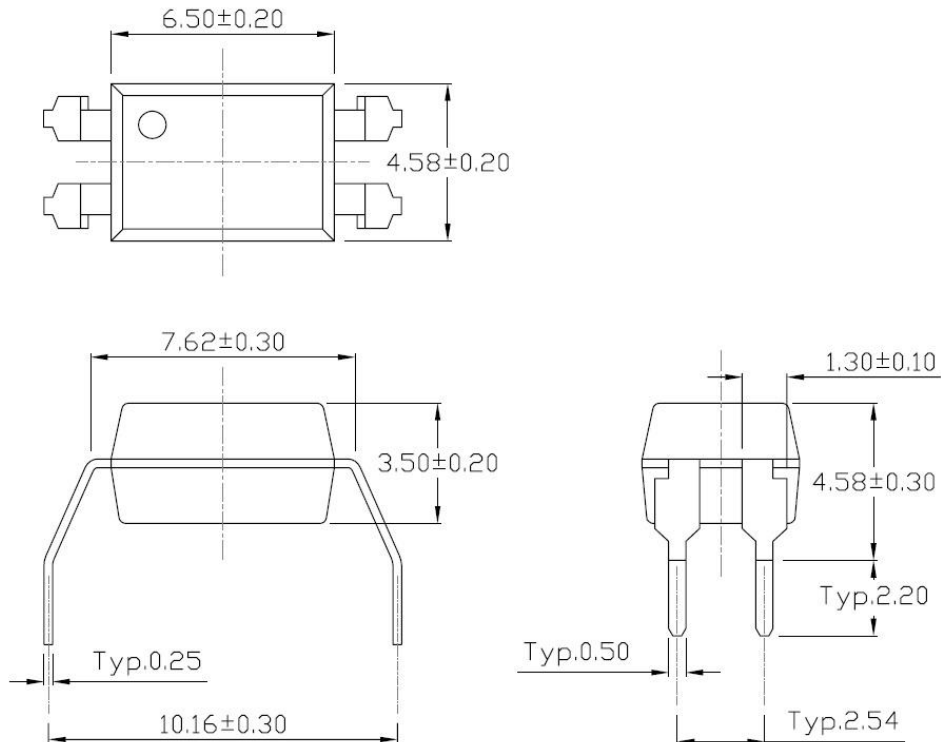
DIP4, DC Input, Photo Transistor Coupler

PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

Standard DIP – Through Hole (DIP Type)



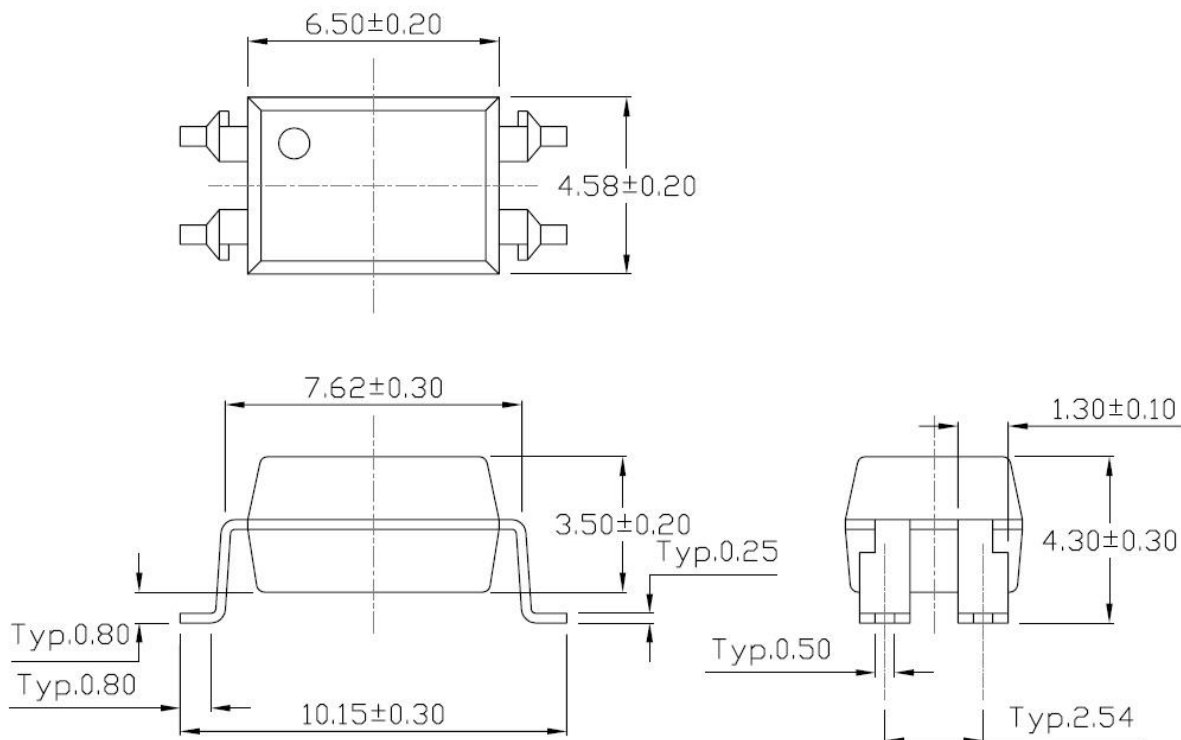
Gullwing (400mil) Lead Forming – Through Hole (M Type)



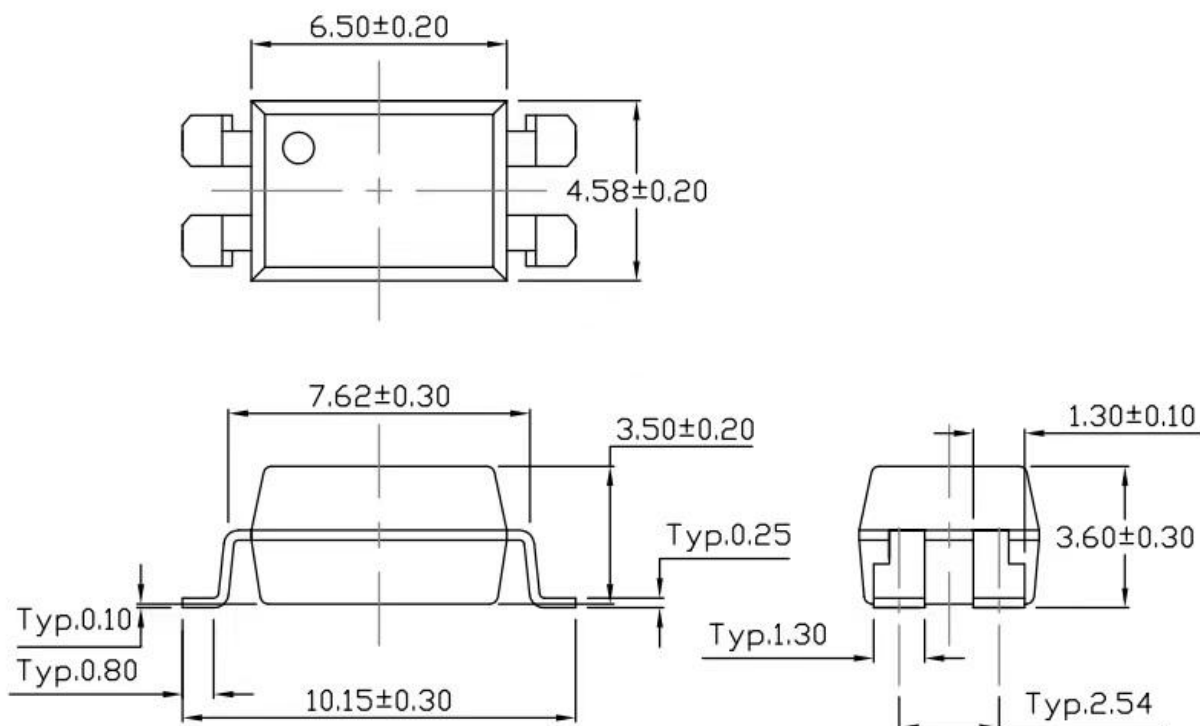
DIP4, DC Input, Photo Transistor Coupler

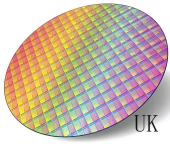
PACKAGE DIMENSIONS (Dimensions in mm unless otherwise stated)

Surface Mount Lead Forming (S Type)



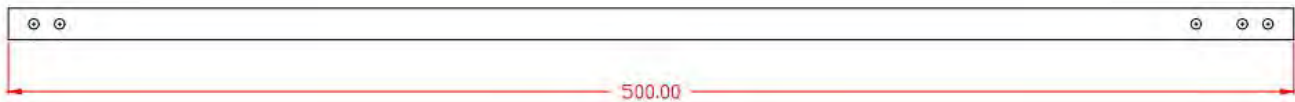
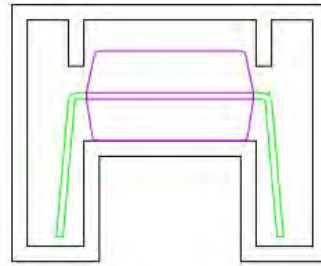
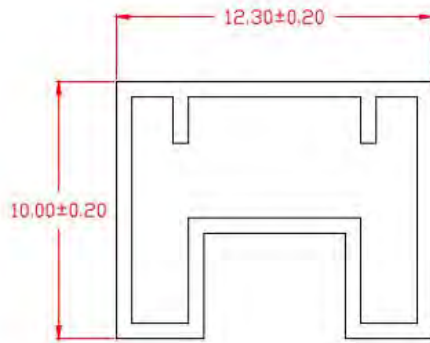
Surface Mount (Low Profile) Lead Forming (SM Type)

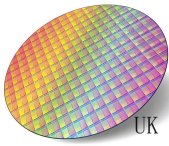




TUBE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

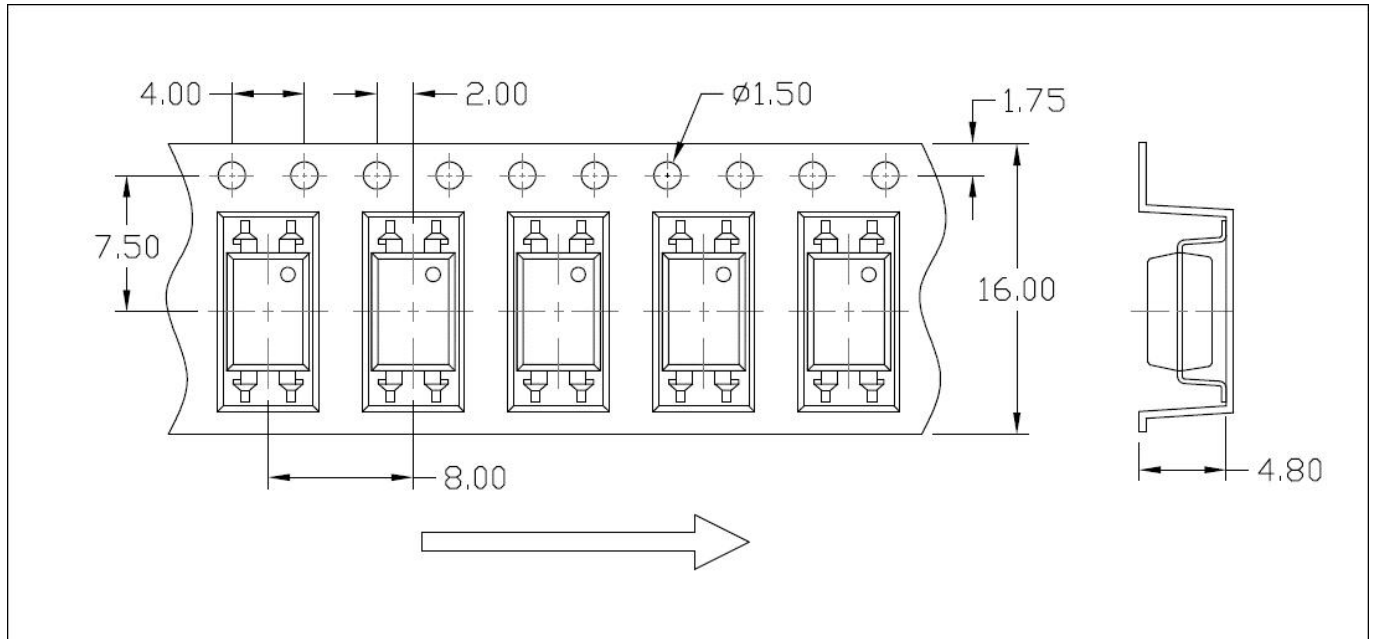
Standard DIP / M



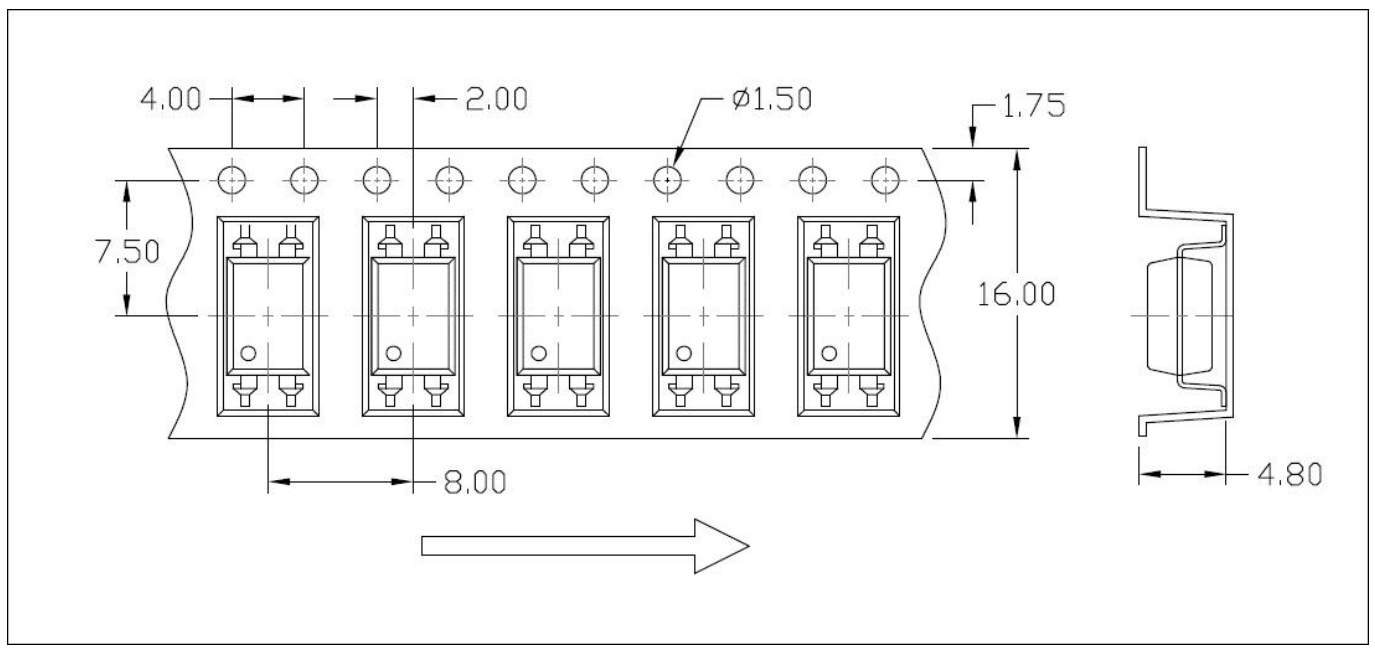


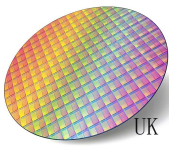
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S(T1) & SM(T1)



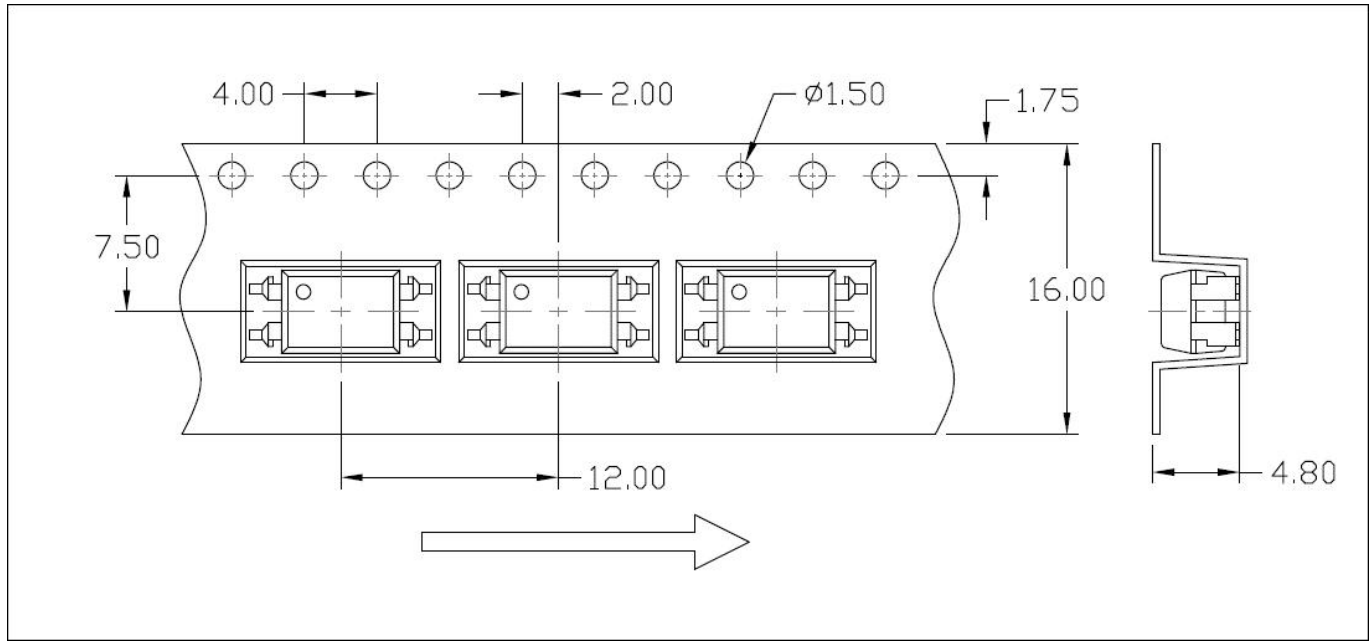
Option S(T2) & SM(T2)



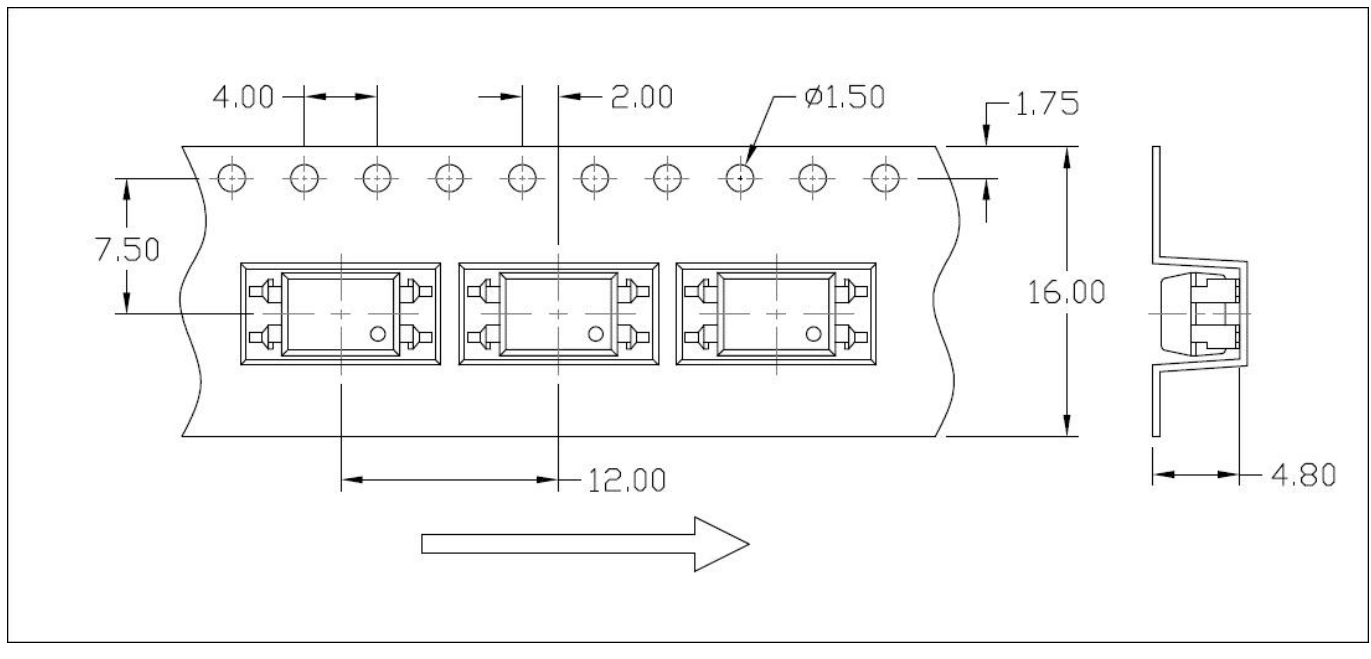


CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S(T3) & SM(T&R)

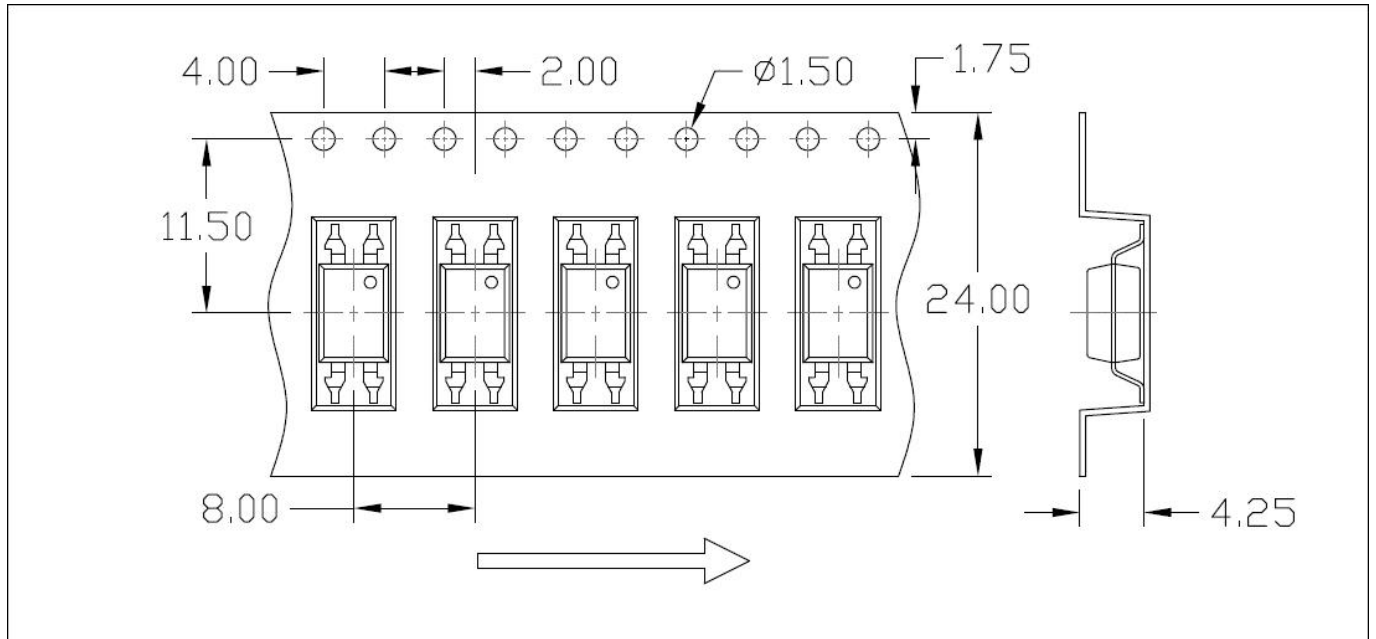


Option S(T4) & SM(T/R)

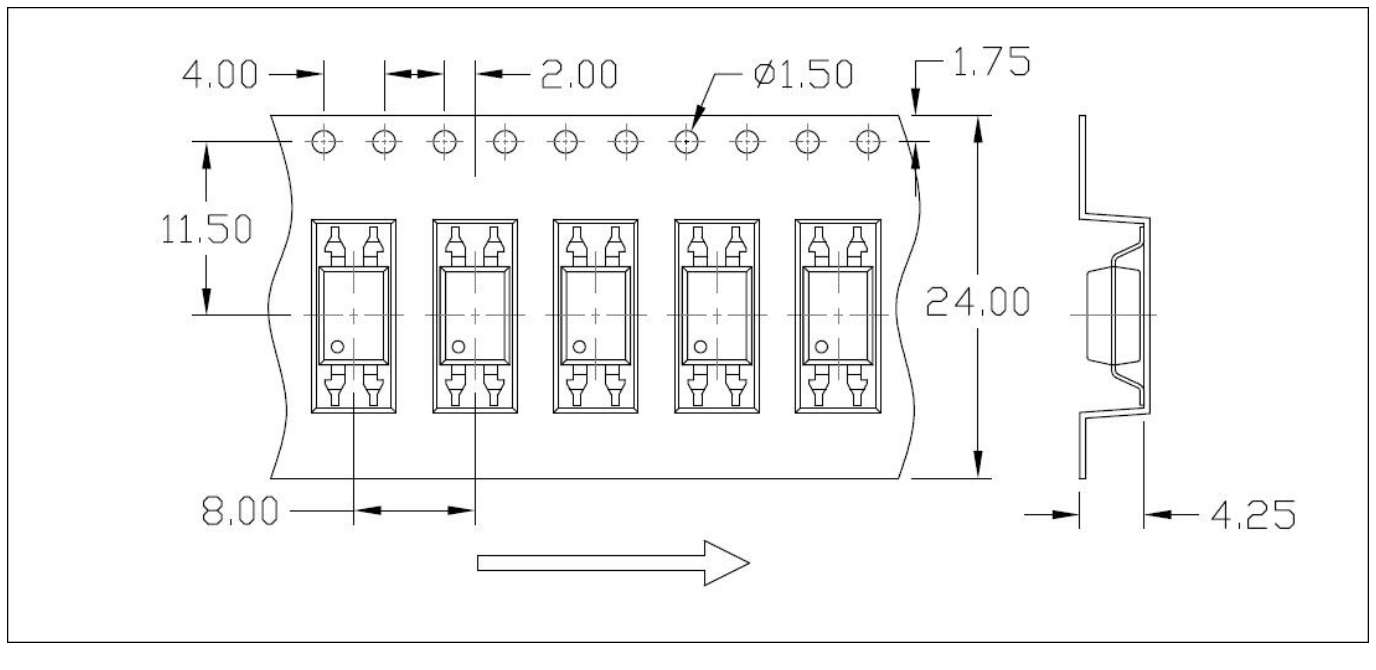


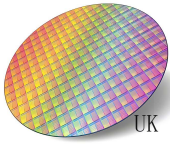
CARRIER TAPE SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option SLM(T1)



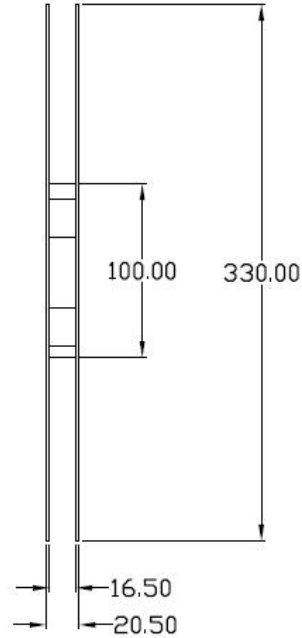
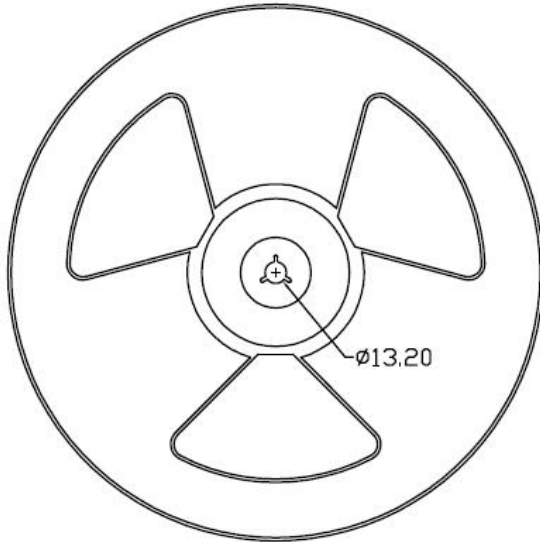
Option SLM(T2)



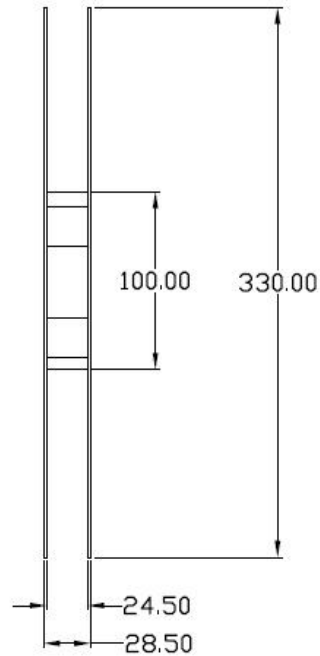
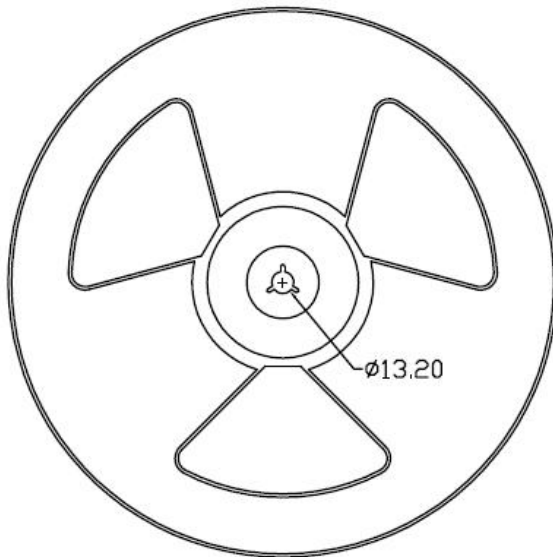


REEL SPECIFICATIONS (Dimensions in mm unless otherwise stated)

Option S & Option SM

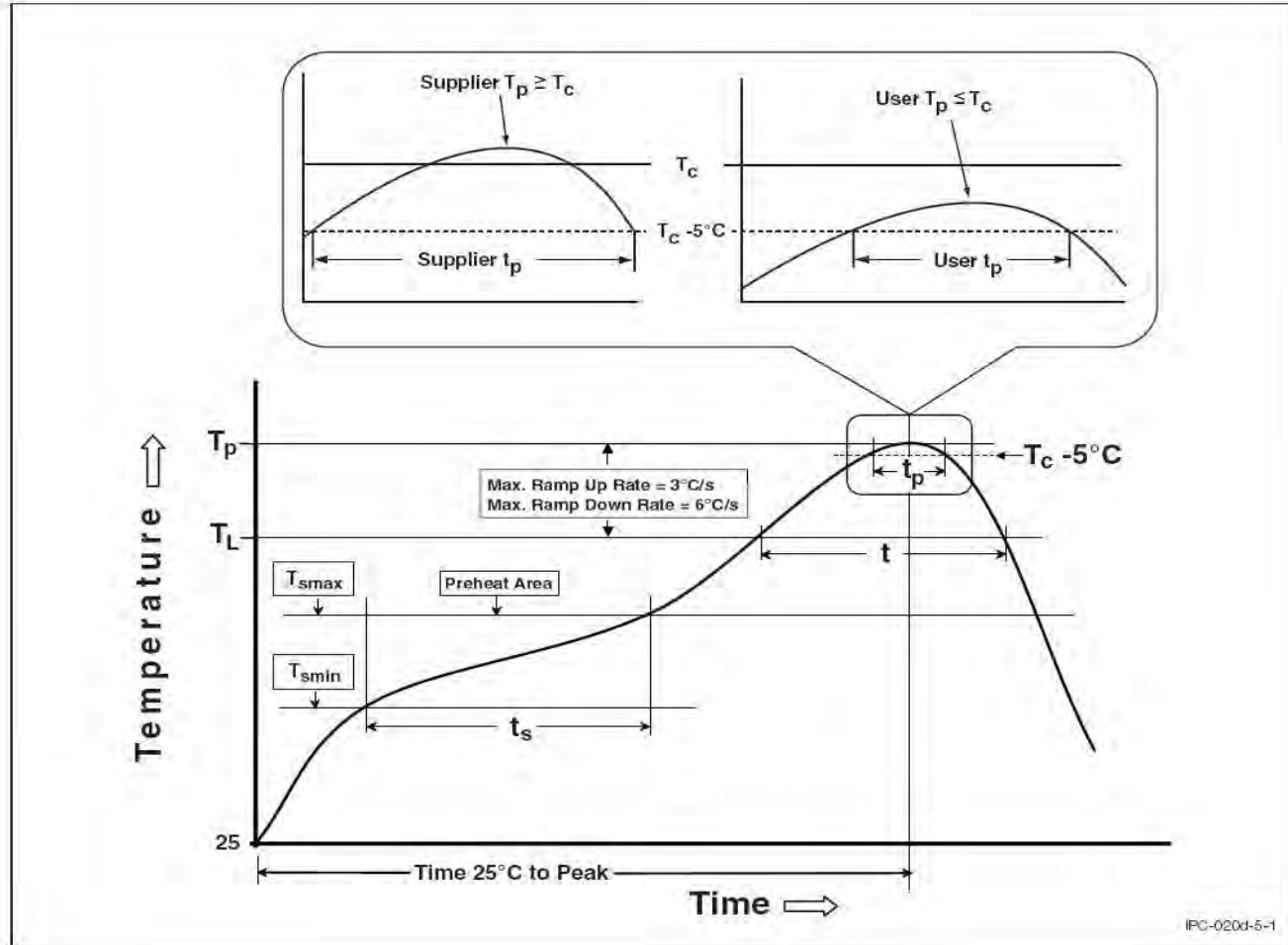


Option SLM

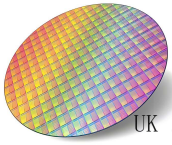


REFLOW INFORMATION

REFLOW PROFILE



Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T _{smin})	100	150°C
Temperature Max. (T _{smax})	150	200°C
Time (t _s) from (T _{smin} to T _{smax})	60-120 seconds	60-120 seconds
Ramp-up Rate (t _L to t _P)	3°C/second max.	3°C/second max.
Liquidous Temperature (T _L)	183°C	217°C
Time (t _L) Maintained Above (T _L)	60 – 150 seconds	60 – 150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (t _P) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T _P to T _L)	6°C/second max	6°C/second max
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



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